



## Material Content Data Sheet



<b>Sales Product Name</b>				ESD205-B1-02ELS E6327		<b>Issued</b>		27. September 2017	
<b>MA#</b>				MA001029314					
<b>Package</b>				PG-TSSLP-2-3		<b>Weight*</b>		0.21 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	non noble metal	tin	7440-31-5	0.000	0.17		1678		
	noble metal	gold	7440-57-5	0.001	0.65		6500		
	inorganic material	silicon	7440-21-3	0.010	4.82	5.64	48176	56354	
leadframe	non noble metal	nickel	7440-02-0	0.108	51.96	51.96	519639	519639	
wire	non noble metal	copper	7440-50-8	0.001	0.72	0.72	7206	7206	
encapsulation	organic material	carbon black	1333-86-4	0.000	0.19		1894		
	plastics	epoxy resin	-	0.011	5.50		54998		
	inorganic material	silicondioxide	60676-86-0	0.067	32.24	37.93	322406	379298	
leadfinish	noble metal	gold	7440-57-5	0.004	1.77	1.77	17730	17730	
plating	noble metal	gold	7440-57-5	0.004	1.98	1.98	19773	19773	
*deviation	< 10%		Sum in total:			100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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